

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	17917	interpos\$4 with (multiple several second other) with (terminal electrode pad landing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/13 09:57
L2	5038	(chip (integrated adj circuit) semiconductor packag\$3 electronic ic dice die) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/13 09:58
L3	3811	(chip (integrated adj circuit) semiconductor packag\$3 electronic ic dice die) with 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/13 09:59
L4	235	(bga bump ball flipchip microbump stud) with 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/13 09:59